

Customer No.: 31561
Application No.: 10/710,908
Docket No.: 11573-US-PA

AMENDMENTS

In The Claims

1. (currently amended) A chip structure, comprising:
a chip, having an active surface and at least a bonding pad disposed on the active surface;
a first passivation layer, disposed on the active surface, comprising at least a first opening exposing the bonding pad; and
a spacing pad, entirely disposed on the bonding pad within the first opening.
2. (original) The chip structure of claim 1, wherein the structure further comprises a metallic bump pad connected to the spacing pad and covering the peripheral surface around the first opening.
3. (original) The chip structure of claim 2, further comprising a second passivation layer disposed over the first passivation layer such that the second passivation layer comprises at least a second opening that exposes the metallic bump pad.
4. (original) The chip structure of claim 3, further comprising an under-bump metallic layer disposed on the top surface of the metallic bump pad and over the peripheral area around the second opening.
5. (original) The chip structure of claim 4, wherein further comprising a conductive bump connected to the under-bump metallic layer.
6. (original) The chip structure of claim 3, further comprising a conductive bump connected

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to the metallic bump pad.

7. (original) The chip structure of claim 1, further comprising an under-bump metallic layer covering a top surface of the spacing pad and the peripheral area around the first opening.

8. (original) The chip structure of claim 7, further comprising a conductive bump connected to the under-bump metallic layer.

9. (currently amended) A conductive structure on the bonding pad of a chip having an active surface and at least a bonding pad disposed on the active surface, the conductive structure comprising:

a spacing pad, entirely disposed on and within the bonding pad, comprising a first surface and a corresponding second surface such that the first surface is in contact with the bonding pad;

a metallic bump pad, having a base in contact with the second surface of the spacing pad and a planar top surface; and

a conductive bump, having a base in contact with the planar top surface of the metallic bump pad.